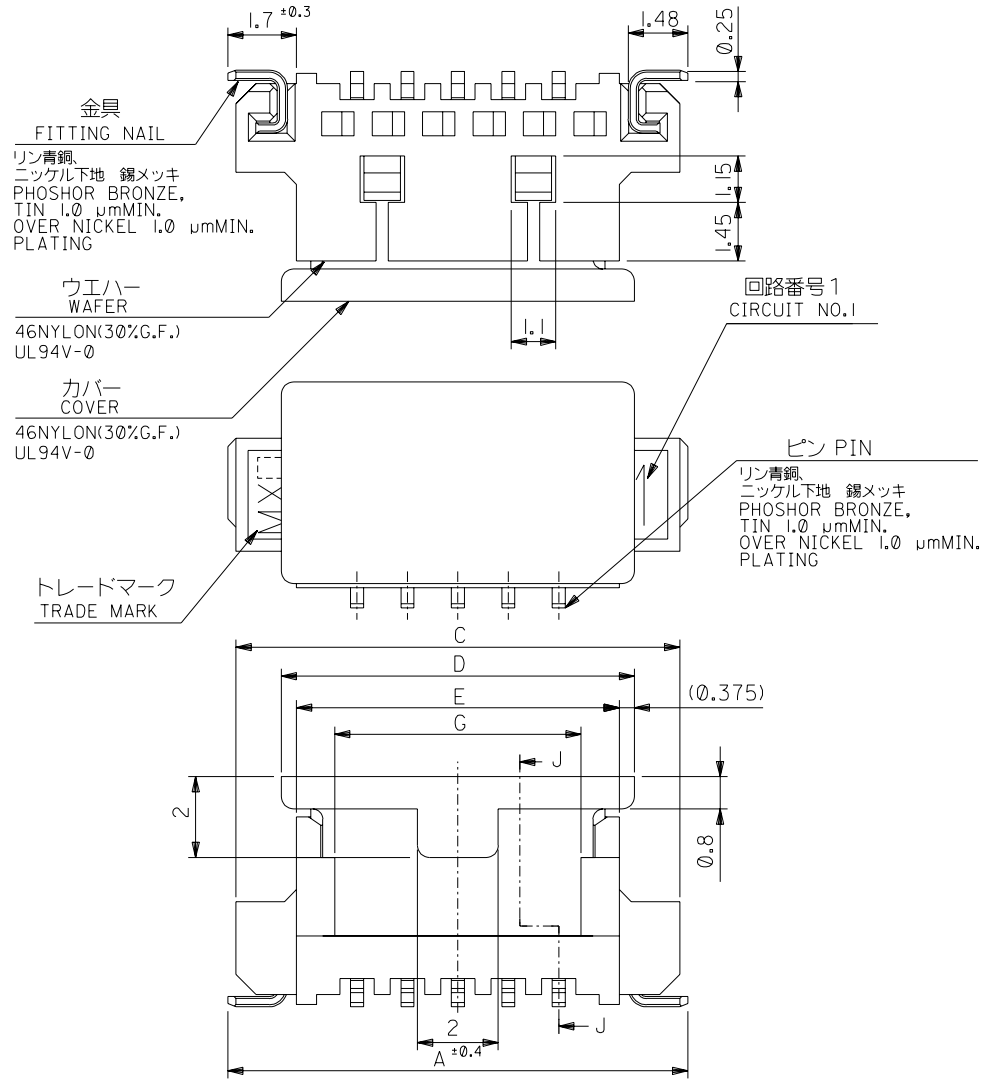
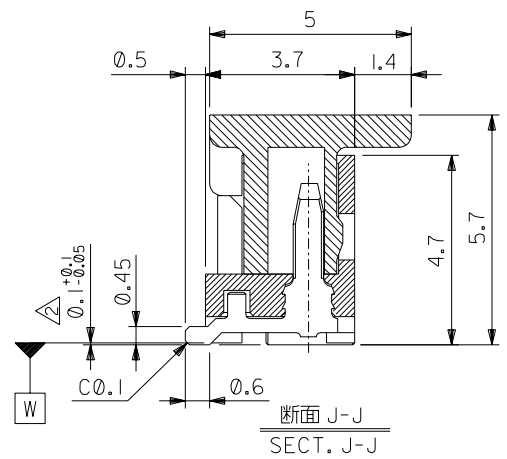


DWG. NO.
SD-53398-034



NOTES

1. 嵌合相手: 51021 シリーズ MATE WITH: 51021 SERIES
2. 水平面上においての、ウェハー底面 $\square W$ とソルダーテール及びフィッティングネイル底面とのズレ量を示す。 MISALIGNMENT OF SOLDER TAIL & FITTING NAIL FROM $\square W$
3. 偶数極のみ適用。APPLY EVEN CIRCUIT PRODUCTS.
4. 本製品は 53398-**20 の鉛フリー品である。 THIS PRODUCT IS LEAD FREE OF 53398-**20.



17.35	18.05	19.25	20	22.25	16.25	22.3	53398-1429	14
14.85	15.55	16.75	17.5	19.75	13.75	20.15	53398-1229	12
9.85	10.55	11.75	12.5	14.75	8.75	15.15	53398-0829	8
8.6	9.3	10.5	11.25	13.5	7.5	13.9	53398-0729	7
7.35	8.05	9.25	10	12.25	6.25	12.65	53398-0629	6
6.1	6.8	8	8.75	11	5	11.4	53398-0529	5
4.85	5.55	6.75	7.5	9.75	3.75	10.15	53398-0429	4
3.6	4.3	5.5	6.25	8.5	2.5	8.9	53398-0329	3
2.35	3.05	4.25	5	7.25	1.25	7.65	53398-0229	2
G	F	E	D	C	B	A	MATERIAL NO.	CIRCUITS

DO NOT SCALE DRAWING

EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. J2004-2404 DRWN: Y.SAKIYAMA CHK: M.SASAO APPR: M.SASAO	RELEASED '04/02/12	MATERIAL 材料 SEE DRAWING	GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	DIMENSIONS: <input type="checkbox"/> mm <input type="checkbox"/> INCH <input checked="" type="checkbox"/> mm ONLY	SHT	REV
							FINISH 仕上げ	10 UNDER 未満 ±0.2	10 OVER 30 UNDER 未満 ±0.25	30 OVER 以上 ±0.3	ANGLE 角度 ±3°	DRAWN BY & DATE Y.SAKIYAMA '04/02/12		
							WIRE RANGE 適用電線範囲					CHECKED BY & DATE M.SASAO '04/02/12		
							INS. RANGE 被覆外径					APPROVED BY & DATE M.SASAO '04/02/12		
												TITLE: 1.25 WIRE TO BOARD CONN. WAFER ASS'Y FOR SMT (ST.) WITH COVER -LEAD FREE-		
												MATERIAL NO. SD-53398-034.S01		
												DRAWING NO. SD-53398-034		
												SHEET NO. 1 OF 2		
												THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.		
												SIZE B		

SD-53398-034.S01

DWG. NO.
SD-53398-034

F

D

C

B

DO NOT SCALE DRAWING

8 7 6 5 4 3 2 1

F

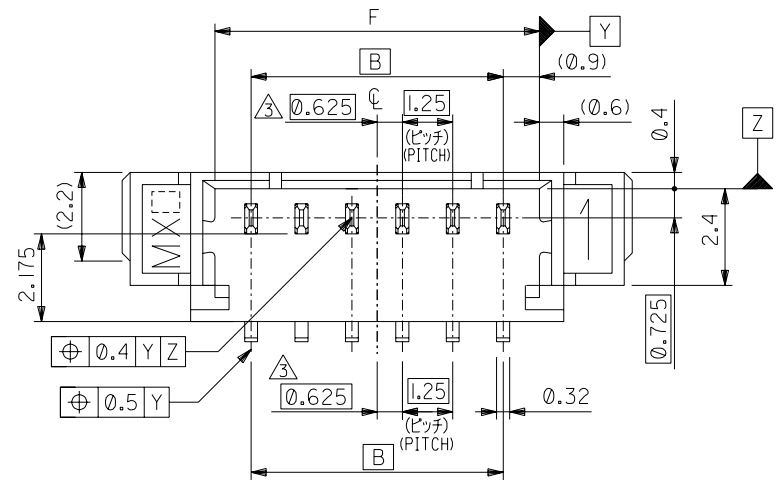
E

D

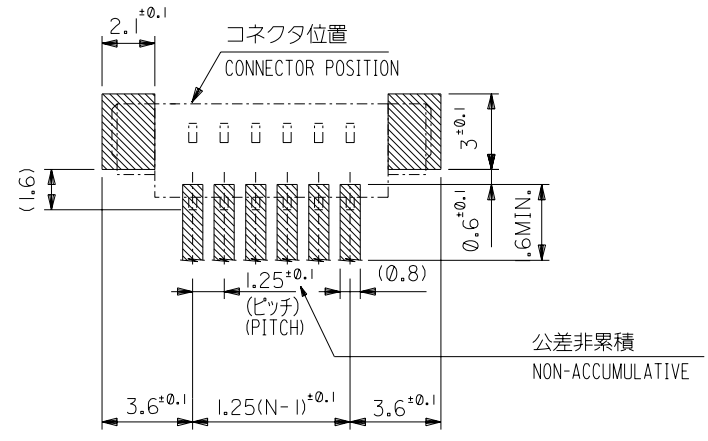
C

B

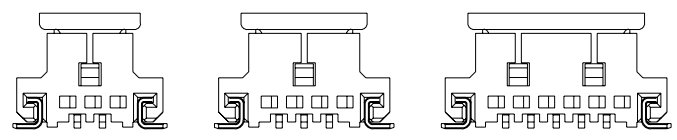
A



カバーなしの場合 (53398-**19)
IN CASE OF WITHOUT COVER



参考基板レイアウト
RECOMMENDED P.C.BOARD PATTERN DIM.(REF.)



△ ロック形状図
LOCK CONFIGURATION

NOTES

△ ロック窓は、2、3極は1ヶ所、4極以上は2ヶ所とする。
LOCKING WINDOW : ONE PLACE FOR 2&3 CKTS.
TWO PLACES FOR MORE THAN 4 CKTS.

EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	RELEASED '04/02/12 EC NO. J2004-2404 DRWN: Y.SAKIYAMA CHK: M.SASAO APPR: M.SASAO	DESCRIPTION	MATERIAL 材料	GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差	SCALE	MODEL NO.	53398-**29	DIMENSIONS:	SHT	REV
							SEE NOTES	10 UNDER 未滿	±0.2	DRAWN BY & DATE Y.SAKIYAMA '04/02/12	THIRD ANGLE PROJECTION	mm INCH	mm ONLY	REVISION ON CAD ONLY
						FINISH 仕上げ	30 UNDER 未滿	±0.25	CHECKED BY & DATE M.SASAO '04/02/12	TITLE: 1.25 WIRE TO BOARD CONN. WAFER ASS'Y FOR SMT (ST.) WITH COVER -LEAD FREE-				
						WIRE RANGE 適用電線範囲	30 OVER 以上	±0.3	APPROVED BY & DATE M.SASAO '04/02/12	MOLEX INCORPORATED				
						INS. RANGE 被覆外径		ANGLE 角度	±3°	CAD FILENAME SD-53398-034.S02	MATERIAL NO. SEE CHART	DRAWING NO. SD-53398-034	SHEET NO. 2 OF 2	SIZE B

SD-53398-034.S02

